



SQUARE PIN SURFACE MOUNT DIODES

These PIN diodes are manufactured in a square package (SMD) for surface mount applications. These packages utilise ceramic package technology with low inductance and axial terminations. This design simplifies automatic pick and place indexing and assembly. The termination contacts are tin lead plated for vapour or reflow circuit board soldering on Printed Circuit Boards.

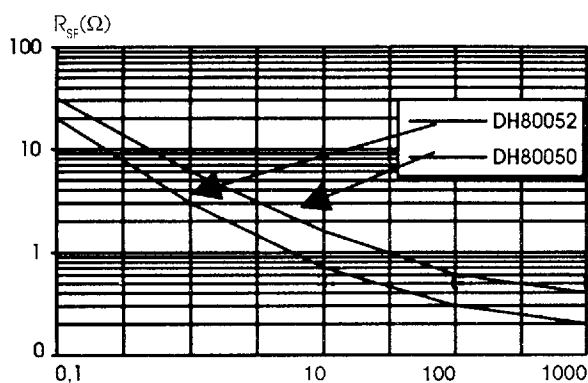
These diodes are particularly suited for applications in frequency hopping radios, low loss, low distortion, and filters in HF, VHF and UHF frequencies. They are available in non-magnetic SMD 4 packages.

CHARACTERISTICS AT 25° C	APPLICABLE VOLTAGE V	BREAK-DOWN VOLTAGE V _{BR}	TOTAL CAPACITANCE C _T		FORWARD SERIES RESISTANCE R _S		MINIORITY CARRIER LIFETIME τ _I	MAX POWER DISSIPATION 25° C	
			f = 1 MHz V _R = 50 V		f = 120 MHz I _F			CONTACT SURFACE (1)	FREE AIR (2)
TEST CONDITIONS	I < 10 μA	I < 10 μA					I _F = 10 mA I _R = 6 mA		
TYPE	V	V	pF		Ω max		μs	W	W
	max	typ	typ	max	I=100 mA	I=200 mA	min	max	max
DH 80050-XX	500	550	0.40	0.45	0.70	0.65	1.1	3.0	1.2
DH 80051-XX	500	550	0.55	0.65	0.60	0.55	1.5	3.5	1.2
DH 80052-XX	500	550	0.85	1.05	0.40	0.35	2.0	4.0	1.2
DH 80053-XX	500	550	1.05	1.20	0.35	0.30	2.5	4.0	1.5
DH 80054-XX	500	550	1.25	1.35	0.30	0.27	3.0	4.5	1.5
DH 80055-XX	500	550	1.45	1.55	0.25	0.22	3.5	4.5	1.5

- (1) Diode brazed on infinite copper heat sink
- (2) Diode brazed on epoxy circuit (PCB)
- (3) Application Note 0020 available on request

TEMPERATURE RANGES :
 Operating Junction (T_j) : -55° C to +175° C
 Storage : -65° C to +200° C

Series Resistance vs. Forward Current



Series Resistance vs. Forward Current

